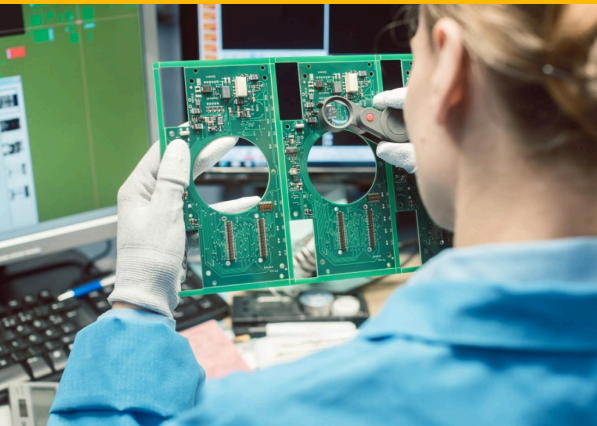


INSPECTION OF ELECTRONIC ASSEMBLIES



This Inspection of Electronic Assemblies: Introduction course trains participants to perform "incoming inspection" using the essential tools, materials, and processes that deliver consistent quality products. Completion of this course delivers a professional level of proficiency in acceptability standards, inspection methods and tools, documentation, and component characteristics.

Who can Participate

An operator, technician or new hire needing foundational training in incoming inspection

Mode of Training

Instructor-Led/In-house Training

Instructor

Master IPC Trainer (MIT) or Certified IPC Trainer (CIT)

Benefits of Participation:

After completing this course, you will be able to employ the key tools, materials, and processes required for inspectors to evaluate Printed Circuit Boards (PCBs) and Printed Circuit Board Assemblies (PCAs) within an electronics manufacturing facility.

Session 1:

- IPC Standards Tree
- Classification of Electronic 'Product's Electronic Assembly Introduction
- Inspection (PCB & PCBA)
- Inspection – Stages
- IPC Acceptability Standard Criteria
- Inspection Methodology

Session 2:

- Inspection Methods
- Incoming Quality Control -IQC
- In-process Inspection
- In-process Inspection- Post Reflow Minimum Electrical Clearance (MEC):

Session 3:

- Through Hole Technology - Inspection
- Surface Mount Technology - Inspection

Session 4:

- Post Assembly Inspection
- Cleanliness, Conformal Coating & potting
- Common Inspection Error- Video

Schedule for Inspection of electronic assemblies

Session No	Session Name	Description
1	Introduction	Registration and Introduction of participants
	General overview of the course and Global Electronics Association Introduction	Presentation
	IPC Standards Tree: Classification of Electronic 'Product's Electronic Assembly Introduction – Inspection (PCB & PCBA): Inspection – Stages: IPC Acceptability Standard Criteria Inspection Methodology:	Presentation
2	Incoming Quality Control -IQC -Inspection Method -AQL -Inspection -Materials, PCB, Component and Hardware In-process Inspection - Baking, - Solder Paste Inspection (SPI) - Pre-Reflow Inspection - Post Pre-Reflow Inspection In-process Inspection- Post Reflow Minimum Electrical Clearance (MEC):	Presentation
	Through Hole Technology -Lead Formation Criteria - Inspection – Leads Protrusion - Inspection – Clinches - Lead Trimming - Inspection - Solder Joint Anomalies	Presentation
3	Surface Mount Technology - Component Types – SMT - Inspection - SMT Components - Inspection- Surface Mount Area Array - Area Array Components – SMT - Solder joint Anomalies- Voids – SMT - Inspection - Component Damage, Adhesive - Inspection - Solder Joint Anomalies -SMT, BGA & Voids Post Assembly Inspection -Inspection - Hardware Installation -Inspection -PCB Inspection -PCB Damages Cleanliness, Conformal Coating & potting. Inspection - FOD (Foreign Object Debris) Inspection - Encapsulation	Presentation
4	Common Inspection Error	Presentation and Video
5	Q&A	Interaction with Instructor

IMPORTANT NOTES

- GST applicable at 18% on the quoted price
- 100% payment to be made before 7 working days of the course commencement
- Minimum 10 & maximum 20 candidates/batch
- Company will share candidates name & details (as per Global Electronics Association format) 7 days in advance before commencement of the course
- Session can be organized on Saturdays
- Participation Certificate shall be provided to the candidates on Global Electronics Association India letterhead
- For In-house Training, Travelling charges to and fro and stay of trainer should be booked by members only

For more information, please reach out to:

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